OVERMOULD™
Specialists in Low Pressure Moulding

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The Fast, Clean, Lower Cost Alternative to Encapsulation & Potting

Encapsulation or potting is the process of pouring liquid resin over electrical and electronic components, circuit boards and completed electronic assemblies for electrical insulation and to protect the product against thermal shock, vibration, moisture and corrosive substances.

Consisting of a 7 - 8 steps process including a curing period, potting can be a messy process that aside from the risk of damage to components, can have many other problems associated with it, not least of which is wastage!

A fast, cleaner and lower cost alternative to encapsulation or potting is Low Pressure Overmoulding.

With just 2 – 3 steps Overmoulding reduces manufacturing time, labour and material costs and improves throughput, resulting in increased ROI. There is zero waste, scrap is often recyclable, and the process is environmentally friendly, giving off no toxic fumes.

The end result is a tamperproof and environmentally sealed product.

Find out more.

Read the answers to some of the most frequently asked questions about the overmoulding process